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APPLICATION NO.	F	ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/659,337		09/11/2003	Hitoshi Haematsu	020721A	0721A 7094	
23850	7590	03/23/2005		EXAMINER		
		ATZ, QUINTOS,	PERKINS, PAMELA E			
	1725 K STREET, NW SUITE 1000				PAPER NUMBER	
WASHINGT	WASHINGTON, DC 20006			2822	· · · · · · · · · · · · · · · · · · ·	
		_		DATE MAILED: 03/23/2009	5	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)				
Office Action Summany	10/659,337	HAEMATSU, HITOSHI				
Office Action Summary	Examiner	Art Unit				
The MAII INC DATE of this communication apr	Pamela E. Perkins	2822				
The MAILING DATE of this communication app Period for Reply	Hears on the cover sneet with the	e correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period/for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).						
Status			•			
1)⊠ Responsive to communication(s) filed on 23 December 2a)□ This action is FINAL. 2b)⊠ This 3)□ Since this application is in condition for allowant closed in accordance with the practice under E	action is non-final.	•				
Disposition of Claims		•				
4) Claim(s) 1-3 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 1-3 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or						
Application Papers	,	·				
9) The specification is objected to by the Examiner 10) The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction of the original of the oath or declaration is objected to by the Examiner	epted or b) objected to by the drawing(s) be held in abeyance. So ion is required if the drawing(s) is a	See 37 CFR 1.85(a). objected to. See 37 CFR 1.121(d).	·			
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Applicantly documents have been received in CPCT Rule 17.2(a)).	ation No ived in this National Stage				
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	· —					
Paper No(s)/Mail Date <u>12/28/04</u> .	6)					

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DETAILED ACTION

This office action is in response to the filing of the request for reconsideration on 23 December 2004. Claims 1-3 are pending.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-3 are rejected under 35 U.S.C. 103(a) as being unpatentable over Harumi (JP 61019154) in view of Hajime (JP 08107120).

Harumi discloses a manufacturing method of a semiconductor device where an electrode is formed on a front face of a semiconductor chip (4); covering the front face the semiconductor chip (4), with a resin insulating film (1); and covering all of an upper surface and side surfaces the resin insulating film (1) with a metal protective film (9) (constitution). Harumi does not disclose forming a plurality of electrodes and providing an electrical connecting portion of at least any of the plurality of electrodes at a reverse face of the semiconductor chip and exposing one of the plurality of electrodes from the upper surface be connected to the metal protective film.

Hajime discloses a manufacturing method of a semiconductor device where a plurality of electrodes (11, 12, 13) are formed on front face of a semiconductor chip; covering the front face of the semiconductor chip with a metal protective film (15),

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wherein a space (19) is left between the front face of the semiconductor chip and the metal protective film (15); and providing an electrical connecting portion of at least any of the plurality of electrodes (13) at a reverse face of the semiconductor chip (para. 22).

Since Harumi and Hajime are both from the same field of endeavor, a manufacturing method of a semiconductor device, the purpose disclosed by Hajime would have been recognized in the pertinent art of Harumi. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Harumi by forming a plurality of electrodes and providing an electrical connecting portion of at least any of the plurality of electrodes at a reverse face of the semiconductor chip as taught by Hajime to operate the circuit with stability and reduce production cost (para. 4).

Referring to claim 2, Harumi discloses forming a metal layer (2) on a peripheral isolation region on front face the semiconductor chip when covering the side surface of peripheral the resin insulating film (1) with the metal film (9) (constitution).

Referring to claim 3, Hajime discloses exposing one of the plurality of electrodes (12) from the upper surface be connected to the metal protective film (15) (para. 23).

Response to Arguments

Applicant's arguments with respect to claims 1-3 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Pamela E. Perkins whose telephone number is (571) 272-1840. The examiner can normally be reached on Monday thru Friday, 9:00am to 5:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may, be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

PEP

AMIR ZARABIAN

PROCESS PATENT EXAMINER

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